- High Current Triacs
- 12 A RMS
- Glass Passivated Wafer
- 400 V to 800 V Off-State Voltage
- Max I<sub>GT</sub> of 50 mA (Quadrants 1 3)

### 

Pin 2 is in electrical contact with the mounting base.

MDC2ACA

### absolute maximum ratings over operating case temperature (unless otherwise noted)

RATING			VALUE	UNIT
Repetitive peak off-state voltage (see Note 1)	TIC236D		400	
	TIC236M	W	600	V
	TIC236S	$V_{DRM}$	700	V
	TIC236N		800	
Full-cycle RMS on-state current at (or below) 70°C case temperature (see Note 2)			12	Α
Peak on-state surge current full-sine-wave at (or below) 25°C case temperature (see Note 3)			100	Α
Peak gate current			±1	Α
Operating case temperature range			-40 to +110	°C
Storage temperature range			-40 to +125	°C
Lead temperature 1.6 mm from case for 10 seconds			230	°C

- NOTES: 1. These values apply bidirectionally for any value of resistance between the gate and Main Terminal 1.
  - 2. This value applies for 50-Hz full-sine-wave operation with resistive load. Above 70°C derate linearly to 110°C case temperature at the rate of 300 mA/°C.
  - 3. This value applies for one 50-Hz full-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.

### electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>D</sub> = Rated V <sub>DRM</sub>	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C			±2	mA
		$V_{\text{supply}} = +12 \text{ V}\dagger$	$R_L = 10 \Omega$	t <sub>p(g)</sub> > 20 μs		12	50	
I <sub>GT</sub>	Gate trigger	$V_{\text{supply}} = +12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		-19	-50	mA
	current	$V_{\text{supply}} = -12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		-16	-50	IIIA
		$V_{\text{supply}} = -12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		34		
		V <sub>supply</sub> = +12 V†	$R_L = 10 \Omega$	t <sub>p(g)</sub> > 20 μs		0.8	2	٧
	Gate trigger	$V_{\text{supply}} = +12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		-0.8	-2	
V <sub>GT</sub>	voltage	$V_{\text{supply}} = -12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		-0.8	-2	
		$V_{\text{supply}} = -12 \text{ V}\dagger$	$R_L = 10 \Omega$	$t_{p(g)} > 20 \mu s$		0.9	2	
V <sub>T</sub>	On-state voltage	I <sub>TM</sub> = ±17 A	I <sub>G</sub> = 50 mA	(see Note 4)		±1.4	±2.1	V
1	Holding current	$V_{\text{supply}} = +12 \text{ V}\dagger$	I <sub>G</sub> = 0	Init' I <sub>TM</sub> = 100 mA		22	40	mA
I <sub>H</sub>		$V_{\text{supply}} = -12 \text{ V}\dagger$	$I_G = 0$	Init' $I_{TM} = -100 \text{ mA}$		-12	-40	

† All voltages are with respect to Main Terminal 1.

NOTE 4: This parameter must be measured using pulse techniques, t<sub>p</sub> = ≤ 1 ms, duty cycle ≤ 2 %. Voltage-sensing contacts separate from the current carrying contacts are located within 3.2 mm from the device body.

### PRODUCT INFORMATION

Information is current as of publication date. Products conform to specifications in accordance with the terms of Power Innovations standard warranty. Production processing does not necessarily include testing of all parameters.



## TIC236 SERIES SILICON TRIACS

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### electrical characteristics at 25°C case temperature (unless otherwise noted) (continued)

	PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
IL	Latching current	$V_{\text{supply}} = +12 \text{ V}^{\dagger}$ $V_{\text{supply}} = -12 \text{ V}^{\dagger}$	(see Note 5)				80 -80	mA
dv/dt	Critical rate of rise of off-state voltage	V <sub>D</sub> = Rated V <sub>D</sub>	I <sub>G</sub> = 0	T <sub>C</sub> = 110°C		±400		V/µs
dv/dt <sub>(c)</sub>	Critical rise of commutation voltage	$V_D$ = Rated $V_D$ di/dt = 0.5 $I_{T(RMS)}$ /ms		$T_{C} = 80^{\circ}C$ $I_{T} = 1.4 I_{T(RMS)}$	±1.2	±9		V/µs
di/dt	Critical rate of rise of on -state current	$V_D$ = Rated $V_D$ di <sub>G</sub> /dt = 50 mA/ $\mu$ s	$I_{GT} = 50 \text{ mA}$	T <sub>C</sub> = 110°C		±100		A/µs

<sup>†</sup> All voltages are with respect to Main Terminal 1.

NOTE 5: The triacs are triggered by a 15-V (open-circuit amplitude) pulse supplied by a generator with the following characteristics:  $R_G = 100 \Omega$ ,  $t_{p(g)} = 20 \mu s$ ,  $t_r = \le 15 ns$ , f = 1 kHz.

### thermal characteristics

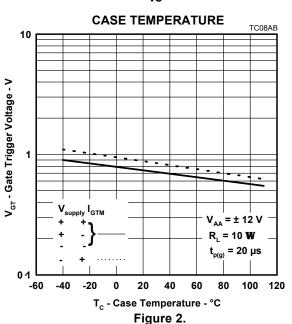
	PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			2	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

### TYPICAL CHARACTERISTICS

### ٧S **CASE TEMPERATURE** TC08AA 1000 <sub>Gт</sub> - Gate Trigger Current - mA 100 10 1 $V_{AA} = \pm 12 V \equiv$ R<sub>L</sub> = 10 **W** $= 20 \mu s$ 0.1 20 80 120 -60 -40 -20 0 40 100 ${\rm T_{\rm c}}$ - Case Temperature - °C

**GATE TRIGGER CURRENT** 

## GATE TRIGGER VOLTAGE vs



### PRODUCT INFORMATION

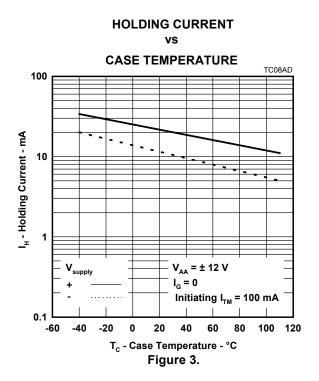
Figure 1.

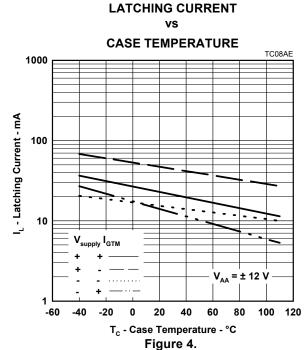


# TIC236 SERIES SILICON TRIACS

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### **TYPICAL CHARACTERISTICS**





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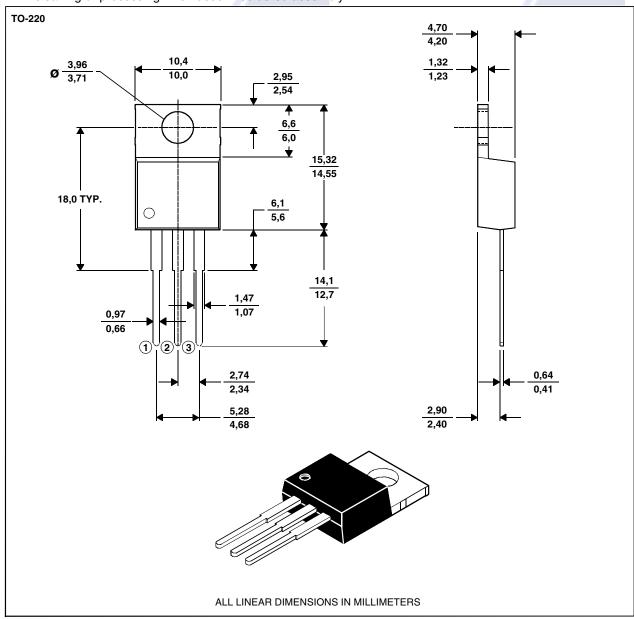


### **MECHANICAL DATA**

### **TO-220**

### 3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.

### PRODUCT INFORMATION



## TIC236 SERIES SILICON TRIACS

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